

Docket No.: P2000,0361

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : WOLFGANG DICKENSCHIED ET AL.
Filed : CONCURRENTLY HEREWITH
Title : METHOD FOR CHARACTERIZING AND SIMULATING A
CHEMICAL MECHANICAL POLISHING PROCESS

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

U.S. Patent No. 5,599,423 (Parker et al.), dated February 4, 1997;

U.S. Patent No. 6,159,075 (Zhang), dated December 12, 2000;

U.S. Patent No. 6,057,068 (Raeder et al.), dated May 2, 2000;

PCT WO 99/25520 (Runnels et al.), dated May 27, 1999;

Smith, T.H. et al.: "A CMP Model Combining Density and Time Dependencies",
Proc.CMP-MIC, 1999, 8 pages;

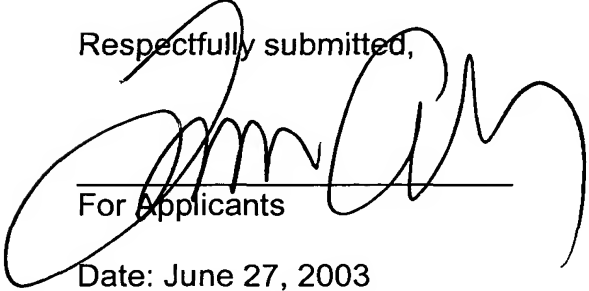
Ouma, D. et al.: "An Integrated Characterization and Modeling Methodology for CMP
Dielectric Planarization", Massachusetts Institute of Technology, 3 pages;

Stine, B. et al.: "A Closed-Form Analytic Model for ILD Thickness Variation in CMP
Processes", Proc.CMP-MIC, 1997, pp. 1-7;

International Search Report, dated January 30, 2003.

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications, patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,



For Applicants

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Date: June 27, 2003

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FORM PTO-1449 (SUBSTITUTE) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.98(b))				Attorney Docket No.: P2000,0361 Appl. No.: <hr/> Applicant: WOLFGANG DICKENSCHIED ET AL. <hr/> Filing Date: June 27, 2003 Group Art Unit:			
EXAMINER INITIALS		PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE
	A	5,599,423	2/4/97	Parker et al.			
	B	6,159,075	12/12/00	Zhang			
	C	6,057,068	5/2/00	Raeder et al.			
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FOREIGN PATENT DOCUMENT							
		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRANSL. YES NO
	J	99/25520	5/27/99	WIPO			
	K						
	L						
	M						
	N						
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)							
		Smith, T.H.: "A CMP Model Combining Density and Time Dependencies", Proc.CMP-MIC, 1999, 8 pages					
		Ouma, D. et al.: "An Integrated Characterization and Modeling Methodology for CMP Dielectric Planarization", Massachusetts Institute of Technology, 3 pages					
EXAMINER				DATE CONSIDERED			

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	K						
	L						
	M						
	N						
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)							
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